



Click [here](#) for the 3D model.

Dimensions

| | |
|-----------|---|
| Chip Size | 0603 |
| L | 1.6mm +0.2/-0.15mm (0.063 in +0.008/-0.006 in) |
| W | 0.81mm +0.2/-0.15mm (0.032 in +0.008/-0.006 in) |
| T | 1.02mm MAX (0.04 in MAX) |
| B | 0.41mm +/-0.2mm (0.016 in +/-0.008 in) |

Packaging Specifications

| | |
|--------------------|--------|
| Packaging | Waffle |
| Packaging Quantity | 100 |

General Information

| | |
|------------------|---------------------------------------|
| Series | SMD MIL X7R PRF32535 |
| Style | SMD Chip |
| Description | SMD, Military, Low ESR, MIL-PRF-32535 |
| RoHS | Yes |
| Termination | Gold |
| Failure Rate | N/A |
| Qualifications | MIL-PRF-32535 |
| AEC-Q200 | No |
| Component Weight | 6300 ug |

Specifications

| | |
|---------------------------------|---------------------|
| Capacitance | 0.1 uF |
| Capacitance Tolerance | 10% |
| Voltage DC | 6.3 VDC |
| Dielectric Withstanding Voltage | 15.75 VDC |
| Temperature Range | -55/+125°C |
| Temperature Coefficient | X7R |
| Dissipation Factor | 7.5% 1 MHz 25C |
| Aging Rate | 3% Loss/Decade Hour |
| Insulation Resistance | 5 GOhms |

单击下面可查看定价，库存，交付和生命周期等信息

[>>KEMET\(基美\)](#)